

T-43-23



GigaBit Logic

10G003  
10G003M

Dual AO/AOI Gate 4-Wide 5,4,3,2 / 2-Wide 3,2  
800 ps Propagation Delay / 1.4 GHz  
**10G PicoLogic™ Family**

**FEATURES**

- Dual AND/NAND gate operation
- 150 ps output rise and fall times
- Active low output enable control (OE)
- ECL and 10G PicoLogic compatible I/O
- Temperature and voltage compensated design
- On-chip VBBS threshold reference voltage supply
- -55/+125°C operation (10G003M)
- Wire-OR output capability
- On chip threshold reference voltage supply (VBBS)
- Available in 40 pin C-leaded or leadless chip carrier or die form
- Packages contain internal decoupling capacitors for optimum high frequency performance

**APPLICATIONS**

- Logic functions including AND/NAND
- Data distribution
- High speed level translator (10G, ECL, TTL/CMOS)
- Precision gating/strobing
- Digital multiplexing

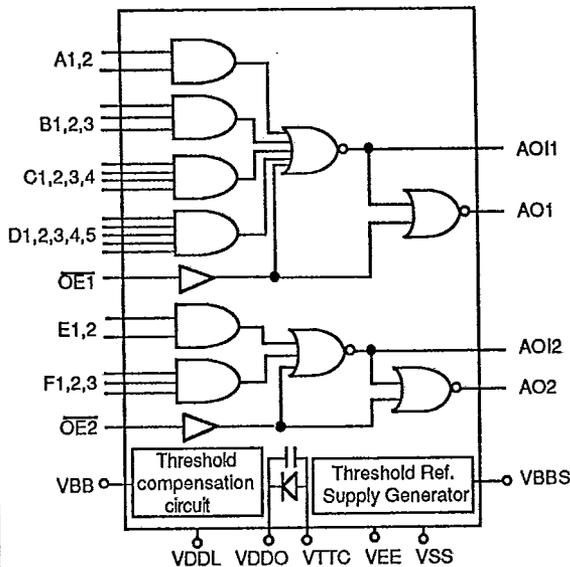
**FUNCTIONAL DESCRIPTION**

The 10G003 is an ultra fast dual AO/AOI gate capable of processing input signals from D.C. to 1.5 GHz. Maximum propagation delay at room temperature is 800 ps, three times shorter than equivalent ECL AO/AOI gates. The 10G003 features an output enable pin (OE) to provide the capability for wired-OR bus connection.

For compatibility with other high speed logic families, the 10G003 features the PicoLogic™ family standard VBB input. This input allows the 10G003's threshold voltage to be controlled by the driving logic family. Therefore, mismatches in threshold level due to temperature and power supply variations can be compensated, providing high system noise immunity. An on-chip threshold voltage output (pin VBBS) is also provided. VBBS must be strapped to the VBB input when PicoLogic™ is used to drive the 10G003.

The 10G003 is a member of GigaBit's PicoLogic™ family of GaAs digital integrated circuits, and is fabricated using GigaBit's high volume GaAs MESFET process technology.

**LOGIC DIAGRAM**



**10G003/10G003M ORDERING INFORMATION**

PACKAGE TYPE	10G003(0°C/85°C)	10G003M (-55/+125°C)
	1.4 GHz	1.2 GHz
C-Leaded CC	10G003 - 2 C	10G003M - 2C
Leadless CC	10G003 - 2 L	10G003M - 2L
Die	10G003 - 2 X	10G003M - 2X

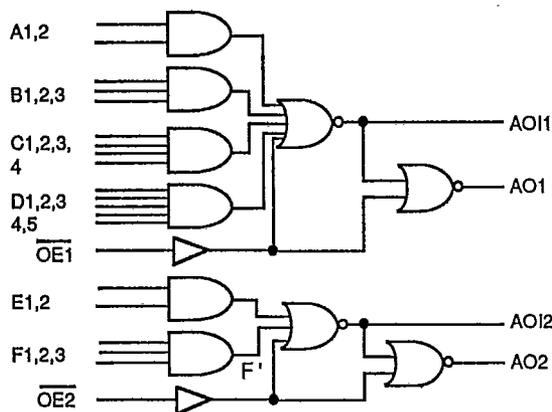
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10G003 Operation



TRUTH TABLE (2-Wide 3,2 AO/AOI)					
$\overline{OE}$	E1	E2	F'	AO2	AOI2
H	X	X	X	0	0
L	X	X	1	1	0
L	X	X	0	E1•E2	$\overline{E1•E2}$

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F' = Output of the 3-input AND gate

Boolean Equations:

$$AO11 = [A1 \cdot A2 \cdot B1 \cdot B2 \cdot B3 \cdot C1 \cdot C2 \cdot C3 \cdot C4 \cdot D1 \cdot D2 \cdot D3 \cdot D4 \cdot D5] \cdot \overline{OE1}$$

$$AO1 = [A1 \cdot A2 + B1 \cdot B2 \cdot B3 + C1 \cdot C2 \cdot C3 \cdot C4 + D1 \cdot D2 \cdot D3 \cdot D4 \cdot D5] \cdot OE1$$

$$AOI2 = [E1 \cdot E2 + F1 \cdot F2 \cdot F3] \cdot \overline{OE2}$$

$$AO2 = [E1 \cdot E2 + F1 \cdot F2 \cdot F3] \cdot OE2$$

The operation of the 2-Wide 3,2 portion of the dual AO/AOI gate is described in the truth table above. All outputs can be forced low by bringing  $\overline{OE}$  input high. If  $\overline{OE}$  is low and F' is 1 (i.e. F1=F2=F3=1), AO2 is 1 and AOI2 is 0, independently of E1 and E2. If  $\overline{OE}$  is low and F' is 0 (i.e. F1=0 or F2=0 or F3=0), AO2 is the AND function for E1 and E2, and AOI2 is the NAND function for E1 AND E2.

Pin Descriptions

An...Fn	Data Inputs	VDCH	Output driver high level clamp voltage. When not used, VDCH should be connected to VDDO. When driving ECL, VDCH may be used to limit VOH. Consult Application Note 4 for detail.
$\overline{OE1}$	Output enable for 5 - 4 - 3 - 2 AO/AOI	VBB	Reference input to the 10G003's input threshold tracking circuit. Connect to the VBB supplied from ECL when driving the 10G003 from ECL. <u>Connect to the VBBS pin when the 10G003 is driven from PicoLogic.</u> This pin cannot be left unconnected.
$\overline{OE2}$	Output enable for 3 - 2 AO/AOI	VBBS	PicoLogic threshold reference output voltage. Connect to VBB when driving from PicoLogic.
AO1	5 - 4 - 3 - 2 AND - OR Output		
AO11	5 - 4 - 3 - 2 ANR - OR - INVERT Output		
AO2	3 - 2 AND - OR Output		
AOI2	3 - 2 AND - OR - INVERT Output		
VDDO	Output driver ground pin (0V)		
VDDL	Internal logic ground connection (0V)		
VSS	-3.4V power supply		
VEE	-5.2V power supply		
VTTC	The AC return pin for the package internal VDDO decoupling capacitor. VTTC is typically tied to VTT (nominally -2.0V)		

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DC CHARACTERISTICS								
VSS = -3.5V to -3.3V, VEE = -5.5V to -5.1V, VDDL=VDDO = 0V, unless otherwise indicated.								
Symbol	Parameter	10G003 (0 to 85°C)			10G003M (-55 to +125°C)			Units
		Min	Typ	Max	Min	Typ	Max	
VIH	Input voltage high				-0.8			V
VIL	Input voltage low						-1.8	V
IIN1	Input current (OE1,OE2)			1000			1000	µA
IIN2	Input current (all others)		150			150	750	µA
VBBS	Threshold reference voltage		-1.2			-1.2		V
ISS	Vss power supply current		170	270		170	300	mA
IEE	Vee power supply current		25	40		25	45	mA
PD	Power dissipation		700	1130		700	1250	mW

**NOTE:**

The remaining DC Characteristics are specified in the 10G PicoLogic™ Family Electrical Characteristics Table at the beginning of this section. This table notes parameter deviations to Family Characteristics and provides specific supplementary characteristics only.

**AC CHARACTERISTICS** (Notes 1, 2)

VSS = -3.5V to -3.3V, VEE = -5.5V to -5.1V, VDDL=VDDO=Gnd., unless otherwise indicated

SYMBOL	PARAMETER	10G003-2						10G003M-2						UNITS		
		Tc= 0°C		Tc= 25°C		Tc= 85°C		Tc= -55°C		Tc= 25°C		Tc= 125°C				
		MIN	MAX	MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	TYP	MAX		MIN	MAX
1/(2T)	Operating Frequency	1.4		1.4	1.5		1.4		1.4		1.4	1.5		1.2		GHz
Tpd1	Input to AOI Output propagation delay	375	725	425	550	725	450	800	450	775	425	550	725	475	850	ps
Tpd2	Input to AO Output propagation delay	450	800	450	650	800	475	850	475	850	450	650	800	500	900	ps
Toe1	OE to Output High to low delay	350	600	350	475	600	375	675	375	650	350	475	600	425	725	ps
Toe2	OE to Output Low to High delay	350	600	350	475	600	375	675	375	650	350	475	600	425	725	ps
T r,f	Output rise and fall time		200		150	200		225		225		150	200		245	ps

**NOTES:**

1. Test conditions (unless otherwise noted): VBB = -1.2V, VTT = -2.0V, VTTC = VTT, Rload = 50Ω to VTT, VDCH = VDDO, VIH = -0.7V, VIL = -1.7V, VOH ≥ -0.7V, VOL ≤ -1.7V. Input signal rise and fall times <150ps.
2. Output rise and fall times are measured at the 20% and 80% points of the transition from VOL max to VOH min.

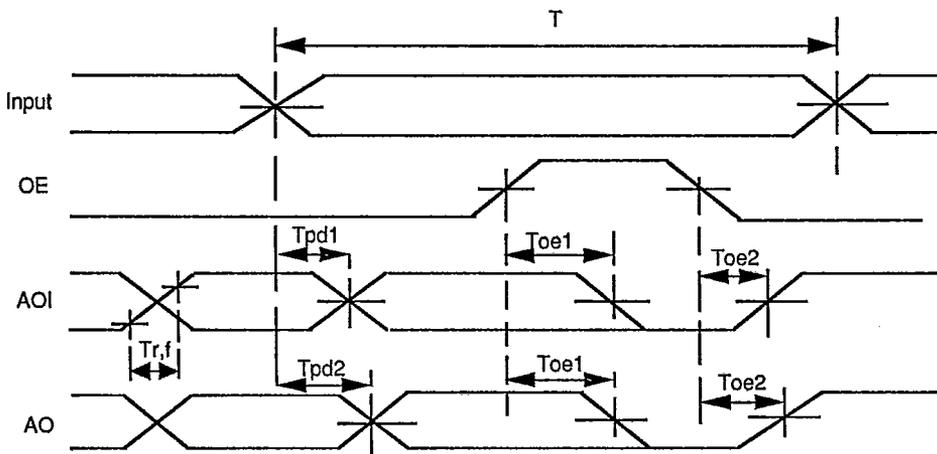
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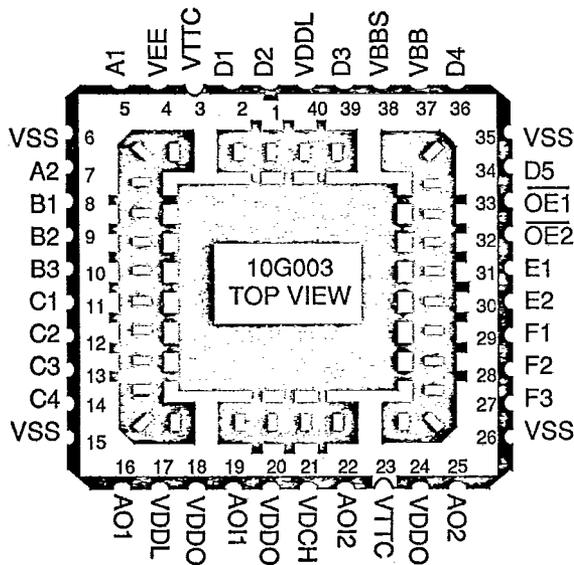
10G003  
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SWITCHING WAVEFORMS



2

PIN FUNCTIONS - TYPE "L" AND "C" PACKAGES

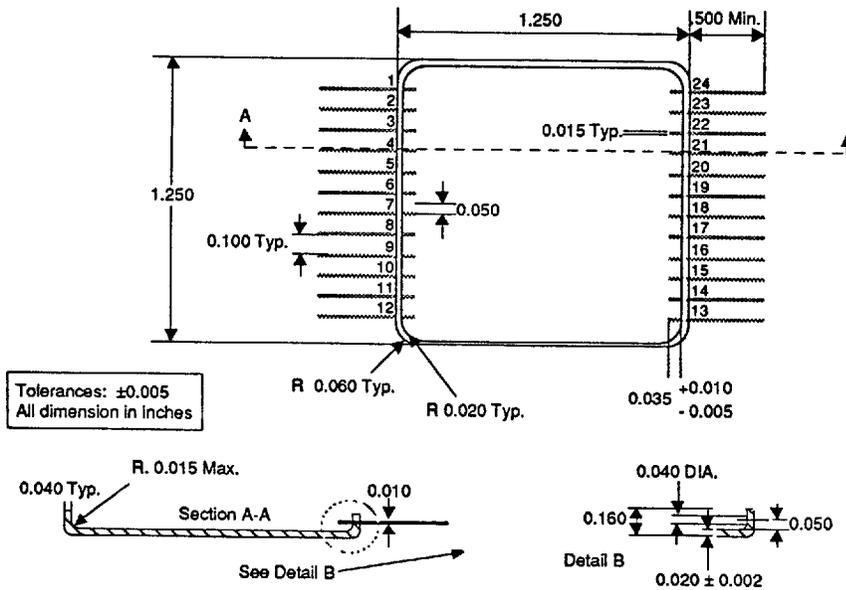


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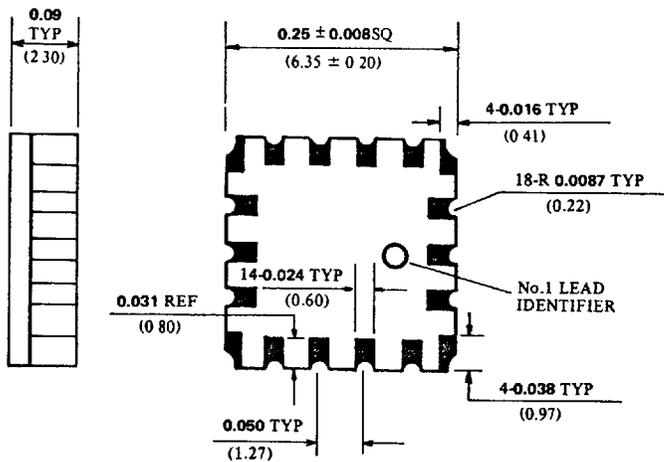


24 PIN METAL FLATPACK  
18 PIN PACKAGE

24 PIN METAL FLATPACK  
Type H



18 PIN LEADLESS CHIP CARRIER  
TYPE L1

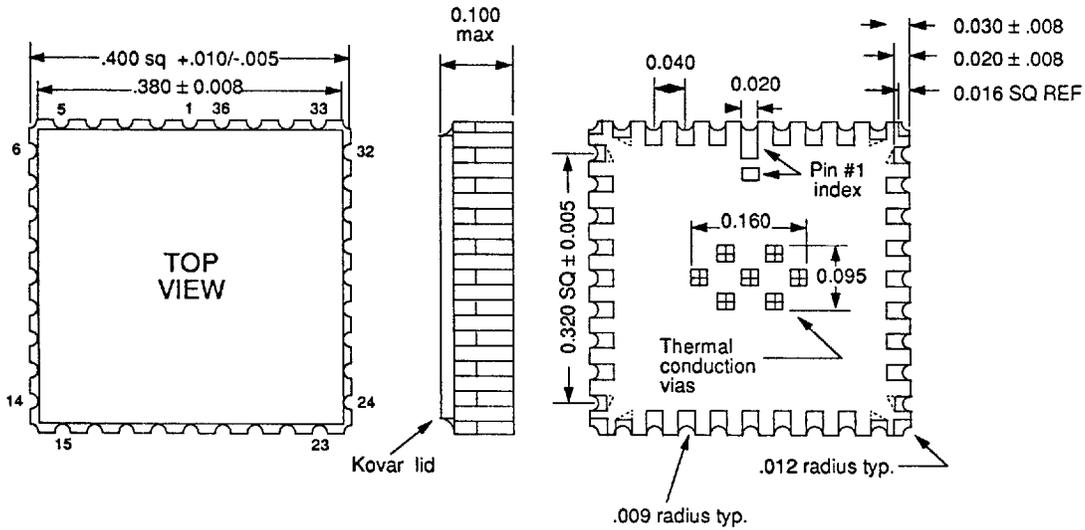


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36 PIN PACKAGES

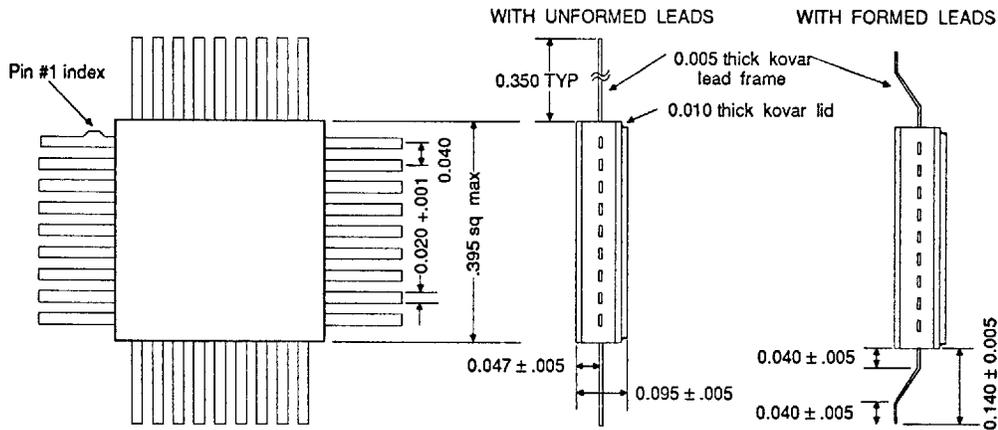
36 PIN LEADLESS CHIP CARRIER  
TYPE L36



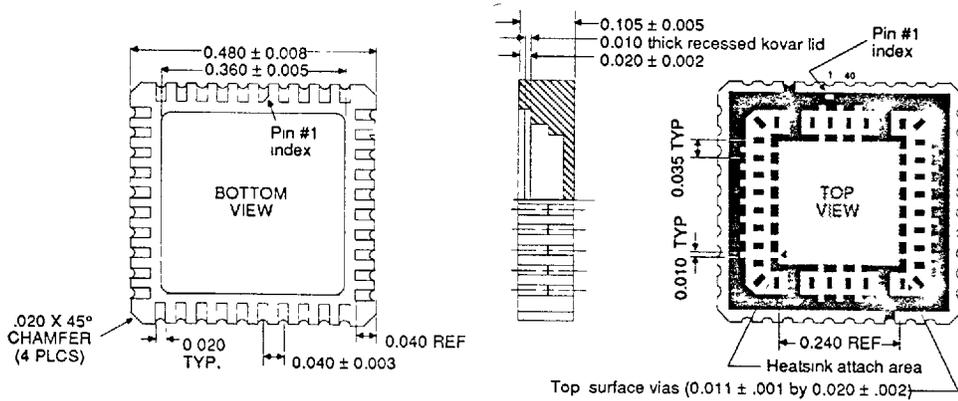
NOTES:

- 1) The package bottom thermal vias, top lid surface and 4 metallized corner castellations (when present) are all at Vss potential.
- 2) All dimensions in inches.
- 3) Pin #1 identifier may be an elongated pad or small, square gray marker.

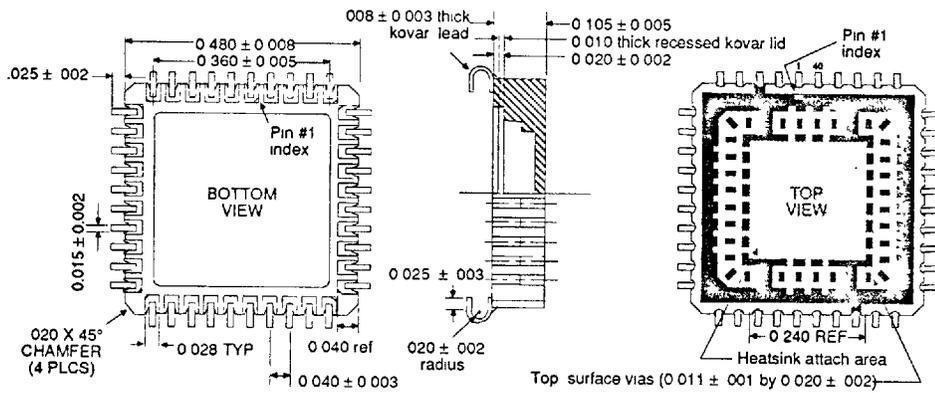
36 I/O LEAD FLATPACK  
TYPE F



**40 PIN LEADLESS CHIP CARRIER  
TYPE L**



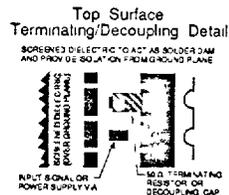
**40 PIN LEADED CHIP CARRIER  
TYPE C**



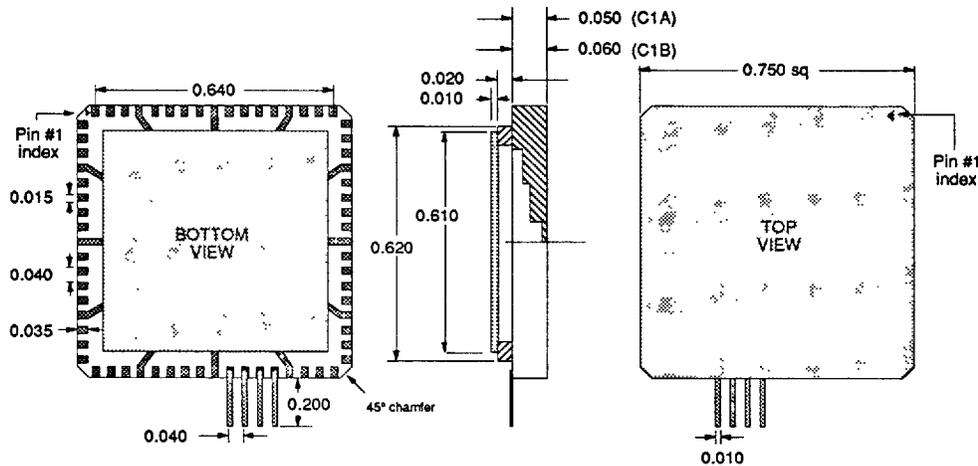
**NOTES**

- (1) Footprint is JEDEC standard outline
- (2) Top surface vias (for terminating resistors and decoupling capacitors) are not available on pins 3, 4, 17, 18, 23, 24, 37, and 38
- (3) Top surface metal (not including vias) and pins 3 and 23 are fixed at VTT potential
- (4) Recommended top surface chip resistors are 0.040 long by 0.020 wide by 0.010 thick typ. 100 mw min. nominal power rating (Mini-Systems MSR 21 or equivalent)
- (5) Recommended top surface chip capacitors are 0.040 long by 0.030 wide by 0.020 thick typ. 25V VCCW 1000 of min. (Johnson R09 caps or equivalent)
- (6) Recommended heat-sinks are GBL P/Ns 90GHS 40 A and 90GHS 40 B
- (7) Thermally conductive, electrically non-conductive epoxy is recommended for heatsink attachment (Ablestick 789 4 or 561K, or Thermalloy Therabond™ or equivalent)
- (8) L40 and C40 packages are dimensionally identical except for contact finger width

TOP SURFACE LEGEND	
Metalized Ceramic	
Screened Dielectric	
Bare Ceramic	

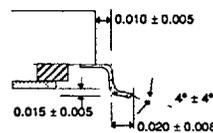


**68 PIN LEADED CHIP CARRIER  
TYPE C1**



1. All dimensions in inches.
2. C1A PACKAGE: Package lid, top, and pins 4, 9, 14, 21, 26, 31, 38, 43, 48, 55, 60, 65 are at common potential (system ground).
3. C1B PACKAGE: Package lid and pins 4, 9, 14, 21, 26, 31, 38, 43, 48, 55, 60, 65 are at common potential (system ground).
4. Tolerance on all dimensions is  $\pm 1\%$  but not larger than  $\pm 0.005$ . Tolerance on 0.640 end pad to end pad dimension is  $\pm 0.003$ .

**GULLWING LEADS**



**132 PIN LEADED CHIP CARRIER  
TYPE C3**

